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MAAP-010168

10 W Power Amplifier
0.5 - 3 GHz

Rev. V2

Features

- Saturated Output Power: +41 dBm
- Linear Gain: 24 dB
- Power Added Efficiency: 30% at P_{SAT}
- 50 Ω Input / Output Match
- Ceramic Flange Mount Package
- RoHS* Compliant and 260°C Re-flow Compatible

Description

The MAAP-010168 is a two stage MMIC power amplifier designed for broadband high power applications. It can be used as either a driver or an output stage amplifier. This device is fully matched input and output to 50 Ω which eliminates any sensitive external RF tuning components.

The device is packaged in a lead free 10-lead flanged package for high volume manufacturing.

The MAAP-010168 is fabricated using a high reliability pHEMT process, to realize good power added efficiency and gain. The pHEMT process features full passivation for high performance and reliability.

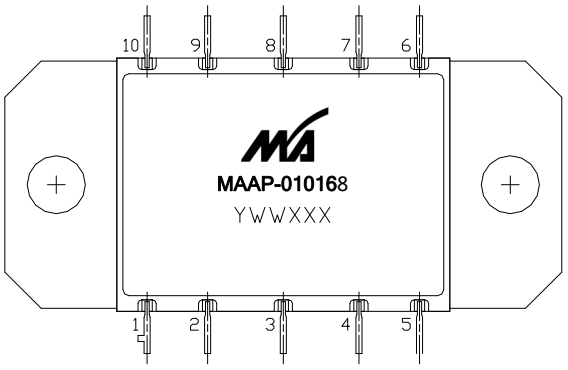
Ordering Information[1]

Part Number	Package
MAAP-010168-000000	Bulk

1. Reference Application Note M567 for package handling and mounting procedure.

* Restrictions on Hazardous Substances, European Union Directive 2002/95/EC.

Functional Schematic



Pin Configuration[2]

Pin No.	Function
1	$V_{GG}2$
2	$V_{GG}1$
3	RF Input
4	$V_{GG}1$
5	$V_{GG}2$
6	$V_{DD}1$
7	$V_{DD}2$
8	RF Output
9	$V_{DD}2$
10	$V_{DD}1$

2. Flange is DC and RF ground.

Handling Procedures

Please observe the following precautions to avoid damage:

Static Sensitivity

Gallium Arsenide Integrated Circuits are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these devices.

• **North America** Tel: 800.366.2266 / Fax: 978.366.2266
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10 W Power Amplifier
0.5 - 3 GHz

Electrical Specifications:
Freq. = 0.5 - 3.0 GHz, V_{DD} = 10 V, I_{DQ} = 3.5 A, T_A = 25 °C, Z_0 = 50 Ω

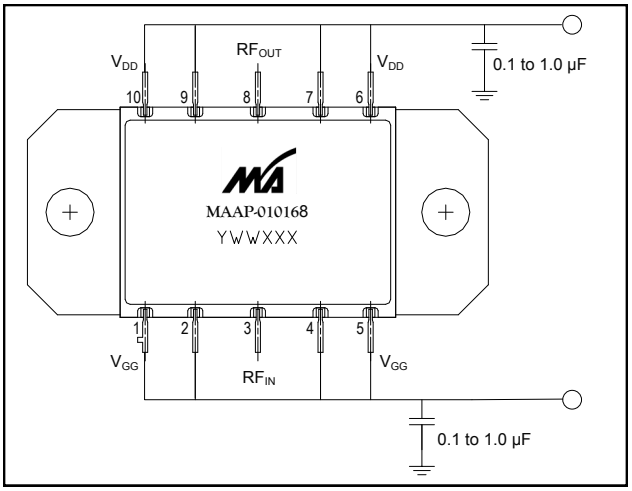
Parameter	Test Conditions	Units	Min.	Typ.	Max.
Gain	Small signal	dB	19	24	—
Input Return Loss	—	dB	—	10	—
Output Return Loss	—	dB	—	10	—
P1dB	—	dBm	—	39	—
P_{SAT}	—	dBm	38	41	—
Current	I_{DQ} P_{SAT}	A	— —	3.5 5.5	— —
PAE	P_{SAT}	%	—	30	—
Gate Bias	—	V	—	-0.7	—
Duty Cycle	—	%	—	—	100

Absolute Maximum Ratings[3,4,5]

Parameter	Absolute Maximum
Input Power	+24 dBm
Operating Supply Voltage	+11 Volts
Operating Gate Voltage	-2 Volts
Operating Temperature	-40°C to +85°C
Channel Temperature[6]	+150 °C
Storage Temperature	-65°C to +150°C

3. Exceeding any one or combination of these limits may cause permanent damage to this device.
4. M/A-COM Technology Solutions does not recommend sustained operation near these survivability limits.
5. Operating at nominal conditions with $T_J \leq +150°C$ will ensure MTTF > 1 x 10^6 hours.
6. Junction Temperature (T_J) = T_C + Θ_{JC} * ((V * I) - (P_{OUT} - P_{IN}))
   Typical thermal resistance (Θ_{JC}) = 2.0°C/W
   a) For T_C = 25°C @ 1.5 GHz
   T_J = +80°C @ +10 V, 4 A, P_{OUT} = 41 dBm, P_{IN} = 21 dBm
   b) For T_C = 85°C @ 1.5 GHz
   T_J = +138°C @ +10 V, 3.9 A, P_{OUT} = 41 dBm, P_{IN} = 21 dBm

Recommended Bias Configuration



Operating the MAAP-010168

The MAAP-010168 is static sensitive. Please handle with care. To operate the device, follow these steps. Ramp down or shutdown in reverse order (gate bias on first and off last). All V_{GG} pins should have the same voltage applied at all times.

1. Apply V_{GG} (-1.5 V).
2. Apply V_{DD} (10.0 V Typical).
3. Set I_{DQ} by adjusting V_{GG}.
4. Apply RF_{IN}.

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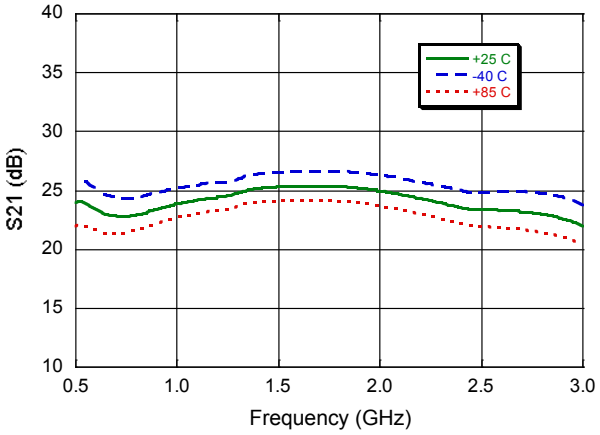
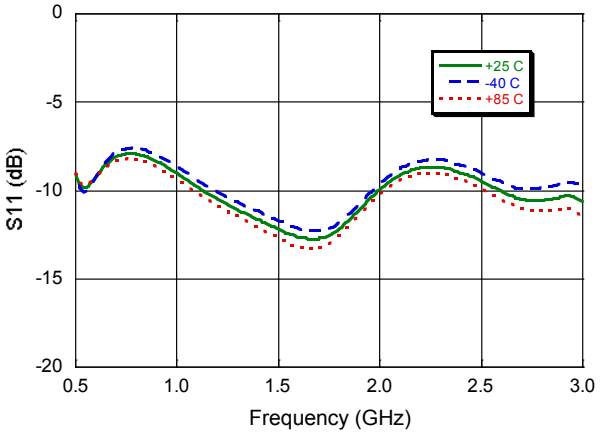
Typical Performance Curves

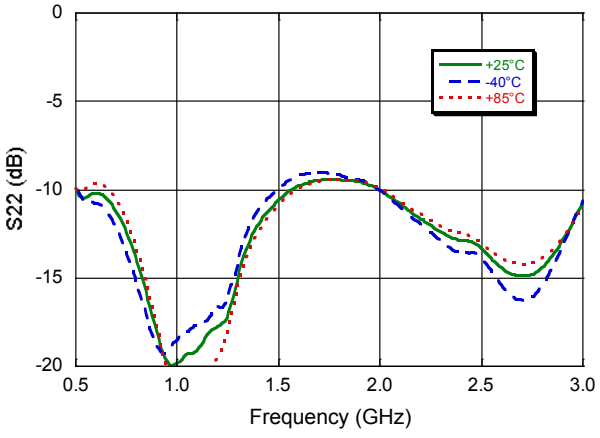
Gain



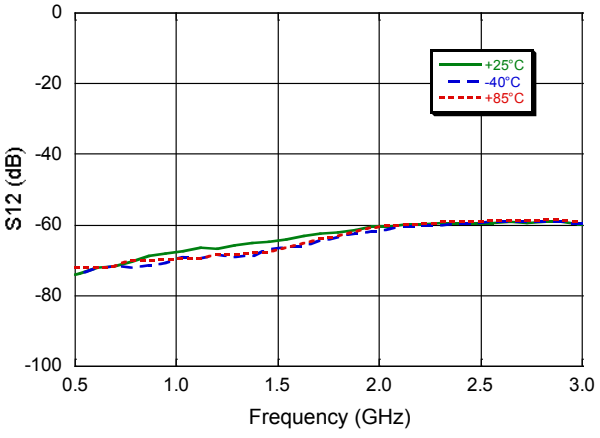
Input Return Loss



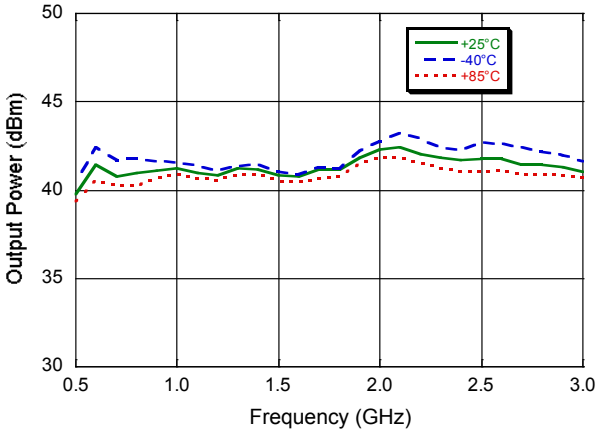
Output Return Loss



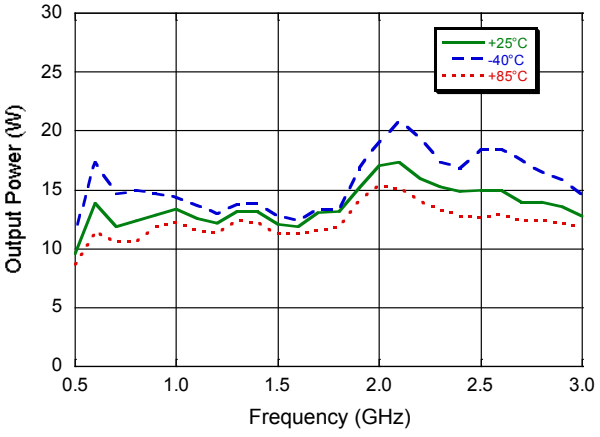
Reverse Isolation



Output Power (dBm)



Output Power (W)



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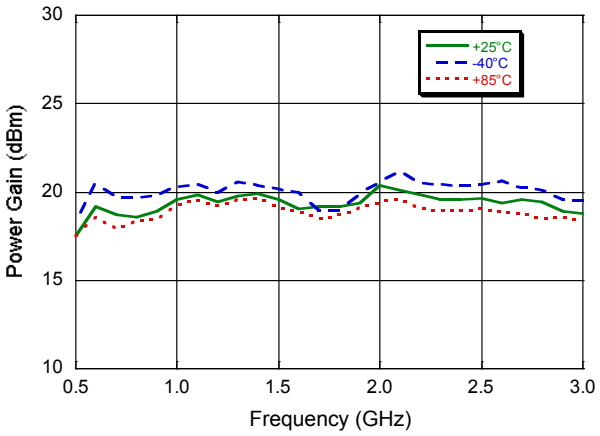
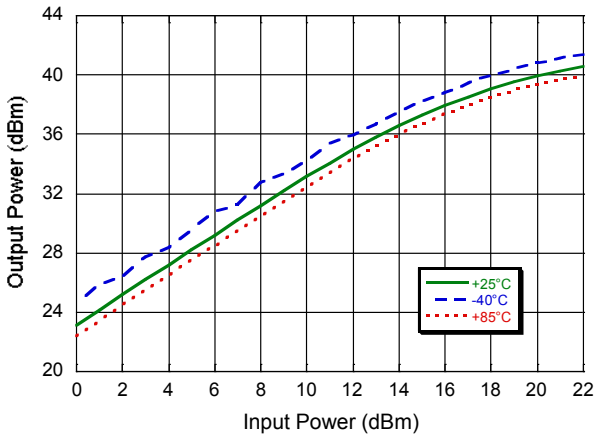
Typical Performance Curves

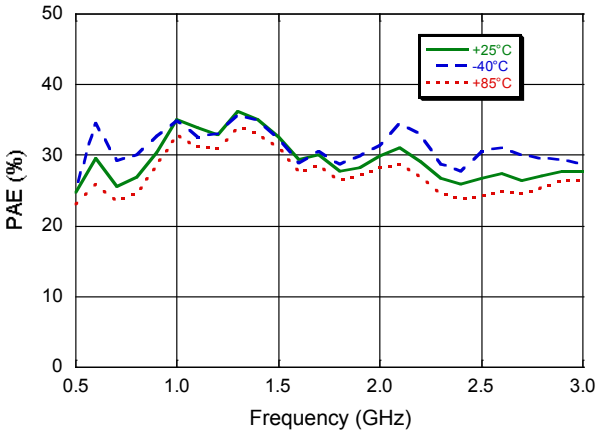
Power Gain



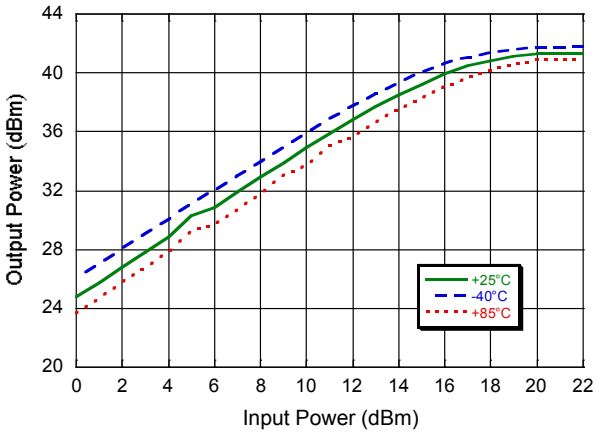
Output Power Sweep @ 0.7 GHz



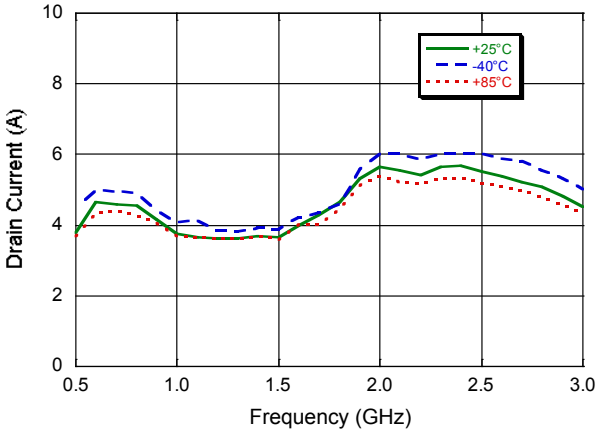
Power Added Efficiency



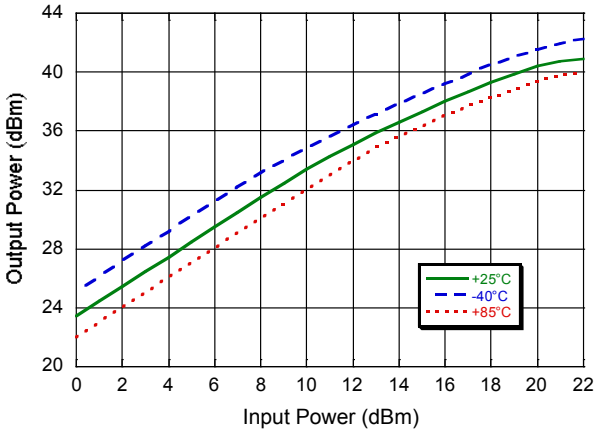
Output Power Sweep @ 1.5 GHz



Drain Current

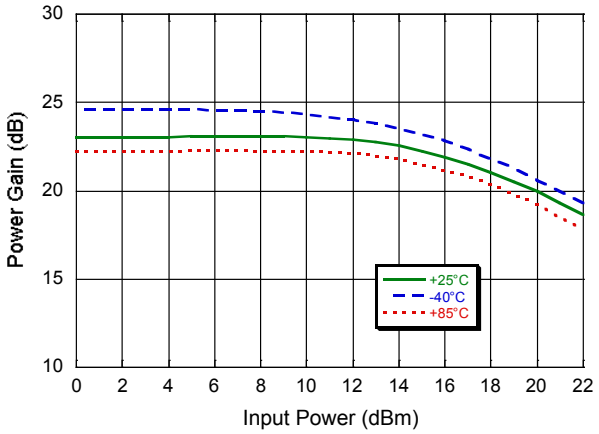


Output Power Sweep @ 2.5 GHz

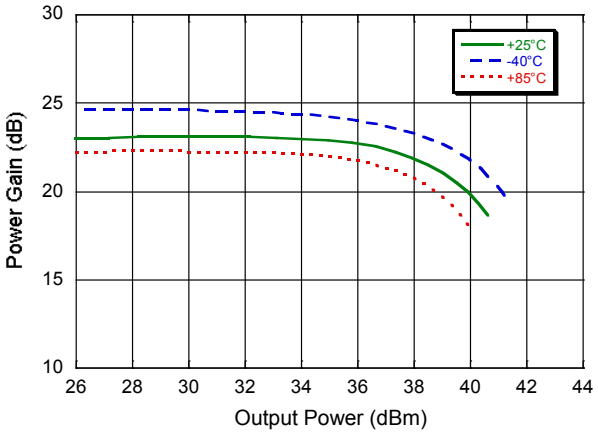


Typical Performance Curves

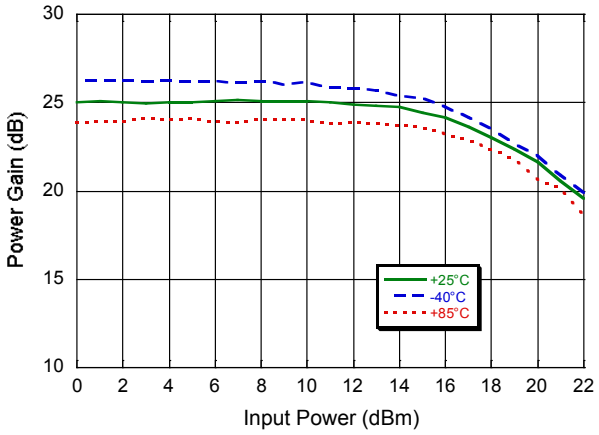
Power Gain vs. Input Power @ 0.7 GHz



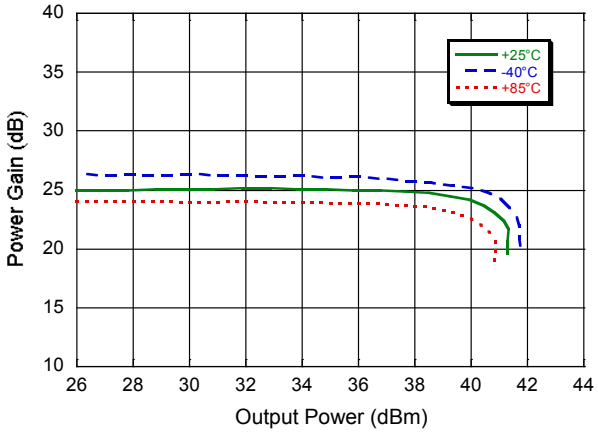
Power Gain vs. Output Power @ 0.7 GHz



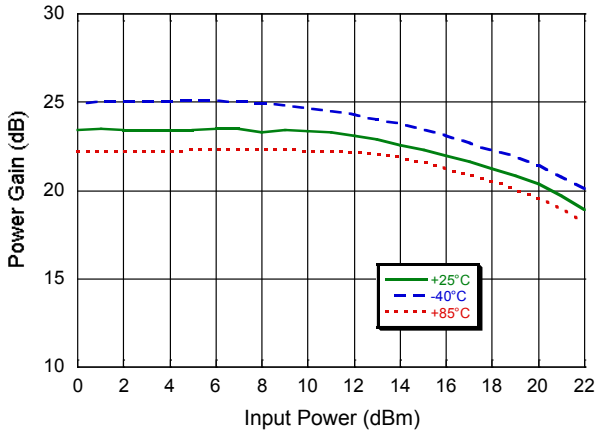
Power Gain vs. Input Power @ 1.5 GHz



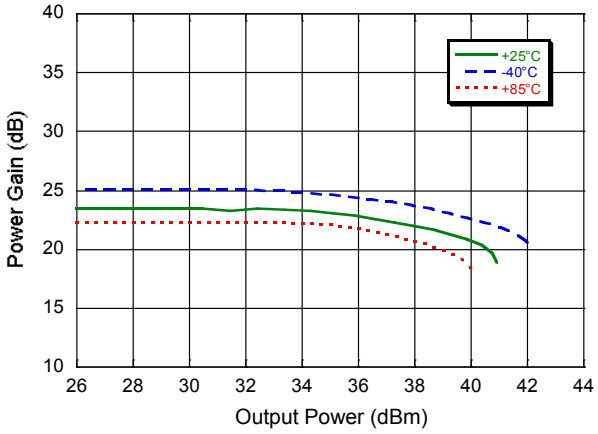
Power Gain vs. Output Power @ 1.5 GHz



Power Gain vs. Input Power @ 2.5 GHz



Power Gain vs. Output Power @ 2.5 GHz



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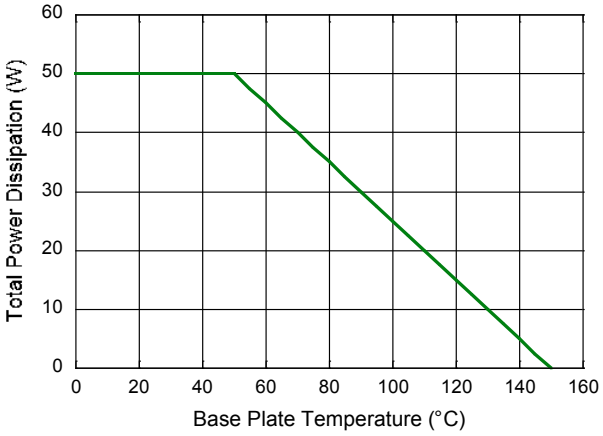
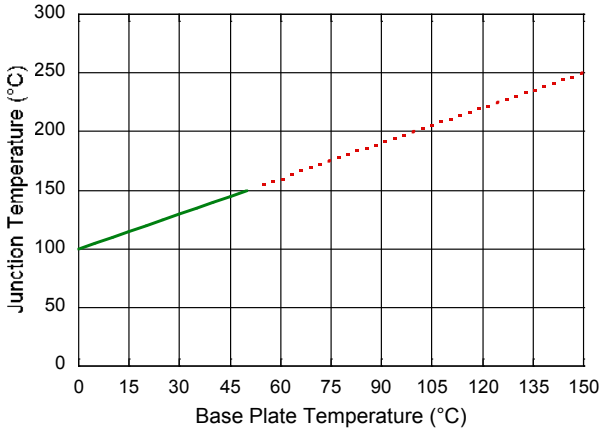
Typical Performance Curves

Max. Power Dissipation vs. Base Plate Temperature[7]

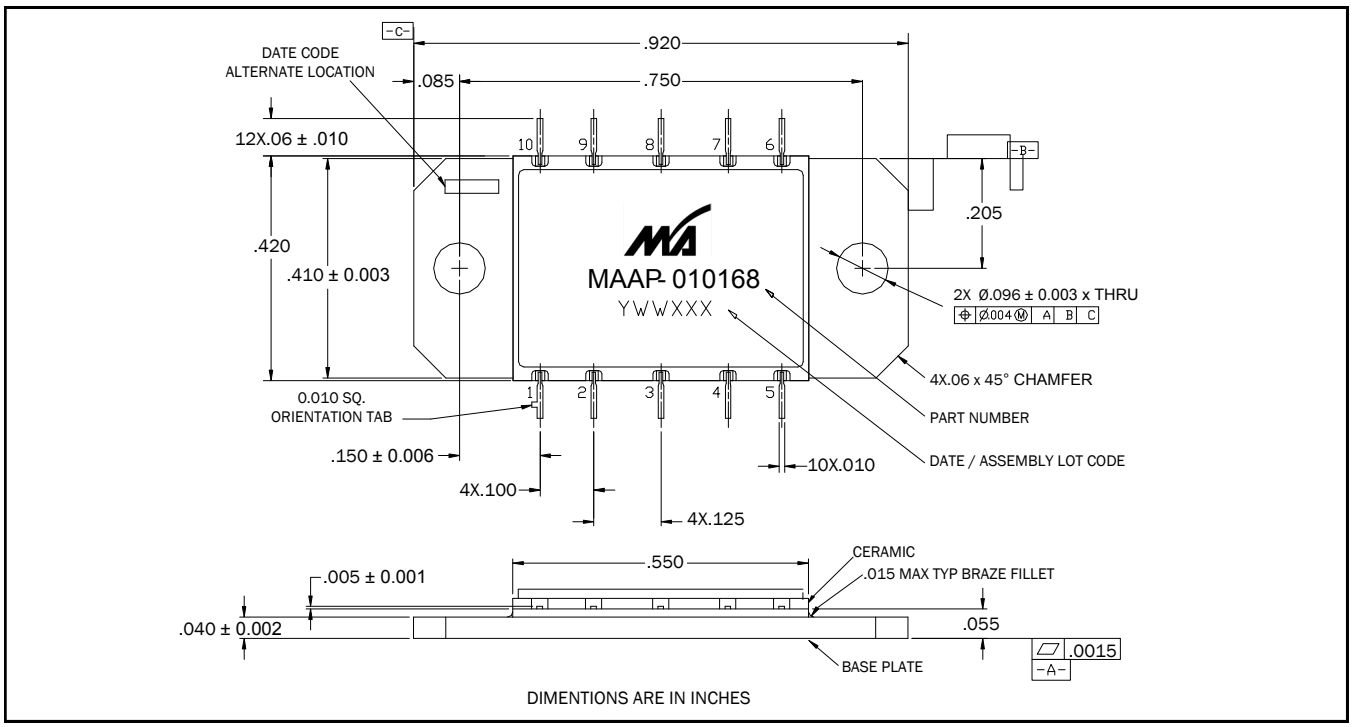


Junction Temperature vs. Base Plate Temperature with 50 W Power Dissipation



7. Power dissipation should not exceed the maximum plot shown above to maintain T_J <150°C. It is recommended to monitor power dissipation and decrease power dissipation in the device as required.

Ceramic Flange Mount Package†



† Reference Application Note M538 for lead-free solder reflow recommendations.
This is a high frequency, low thermal resistance package. The package consists of a cofired ceramic construction with a copper-tungsten base and iron-nickel-cobalt leads. The finish consists of electrolytic gold over nickel plate.

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